



2012 OUTLINE

Description:

The MMA706 is a fully matched amplifier fabricated in Aeroflex / Metelics reliable InGap HBT technology. The economical, low parasitic molded package provides state-of-the-art wideband performance.

Features:

- DC - 6 GHz Broadband Gain Block
- \pm 0.5 dB Typical Gain Flatness
- 50 Ohms Input/Output Impedances •

RF Specifications:

Parameter	Term	Minimum	Typical	Maximum	Units
3dB Bandwidth	BW	DC		9	GHz
Frequency Range	f _o	DC		6	GHz
Gain	G _P	13.5	14.5		dB
Output Power	P _{1dB}	+ 13	+ 14		dBm
Standing Wave Ratio	VSWR		1.5:1	2.0:1	
3 rd Order Intercept Point	IP3	+21	+27		dBm
Noise Figure	NF		3.8	4.2	dB
Device Current	Ι _c	42	45	55	mA

NOTES:

1. $T_A = +25$ °C.

2. $\hat{V}_{s} = 6.0$ Vdc, $R_{BIAS} = 22 \Omega$ 3. IP3 measured with two tones offset 10 MHz at 0 dBm per tone.

Absolute Maximum Ratings:

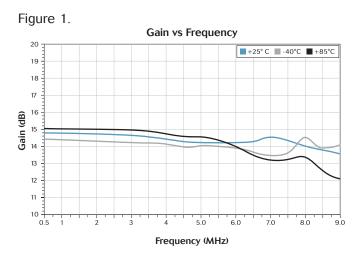
Parameters	Rating		
Device Current (I _c)	80 mA		
RF Input Power, continuous	+10 dBm		
Operating Temperature	-40 to +85 °C		
Storage Temperature	-55 to +125 °C		
Thermal Resistance ($\theta_{_{JC}}$)	125 °C/W		

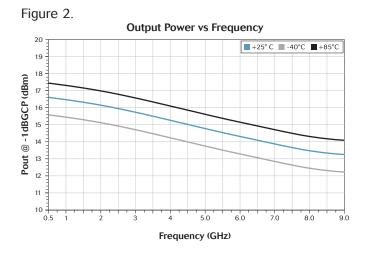


Revision Date: 12/01/04

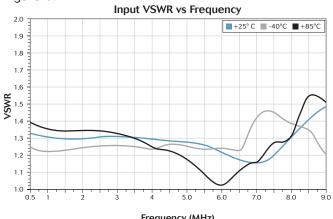


Typical RF Performance:

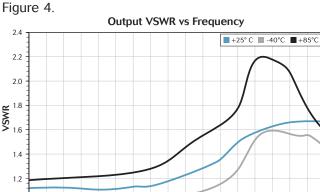








Frequency (MHz)



4

3

2



Group Delay vs Frequency

Frequency (mHz)

5.0

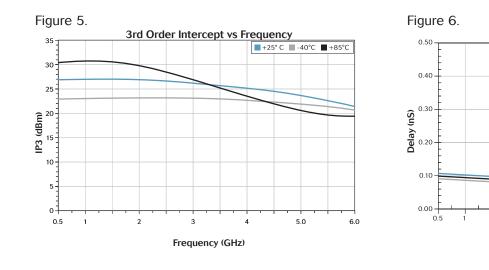
6.0

7.0

8.0

■ +25° C ■ -40°C ■ +85°C

9.0



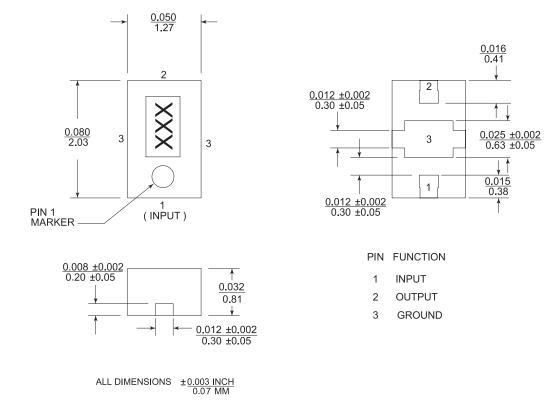
Aeroflex / Metelics, Inc. www.aeroflex-metelics.com

1.0

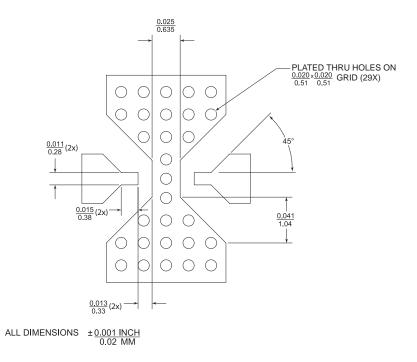
0.5



SOT89 Outline Dimensions:

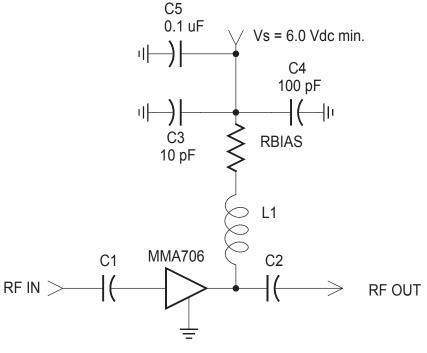


Recommended PCB Layout:





Application Circuit:



C1, C2, L1: X_L >> 50 Ω , X_C << 50 Ω

R _{BIAS} vs. V _S									
V _s (V)	6.0	8.0	10.0	12.0	15.0				
R _{BIAS} (Ω)	22	62	100	150	200				
Power Dissipation (W)	0.05	0.15	0.25	0.34	0.48				

